

MDT070005	1024 x 600	MIPI Interface	TFT Module
Specification			
Version: 1		Date: 25/05/2022	
Revision			
1	23/05/2022	First issue	

Display Features			
Display Size	7.00"		
Resolution	1024x600		
Orientation	Landscape		
Appearance	RGB		
Logic Voltage	3.3V		
Interface	MIPI		
Brightness	1000 cd/m ²		
Touchscreen	---		
Module Size	164.80 x 99.80 x 5.50 mm		
Operating Temperature	-20°C ~ +70°C	Created By	Checked By
Pinout	30 way FFC	CL	WE
Pitch	0.50 mm	Box Quantity	Weight / Display
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* - For full design functionality, please use this specification in conjunction with the EK79007AD2+EK73217BCGA display driver specification.(Provided Separately)

Display Accessories	
Part Number	Description
MBID-30FP	30 way FFC/FPC 0.5mm to 30 way JST 1mm crimp header
MDIB-CC1	Interconnect board for standard pitch pinouts to fine pitch wires. Providing pinouts for 2.54 pinout. 1.27, 1, 0.845, 0.8, 0.7, 0.65, 0.62, 0.6, 0.5 & 0.3 pads.

Optional Variants	
Appearances	Voltage



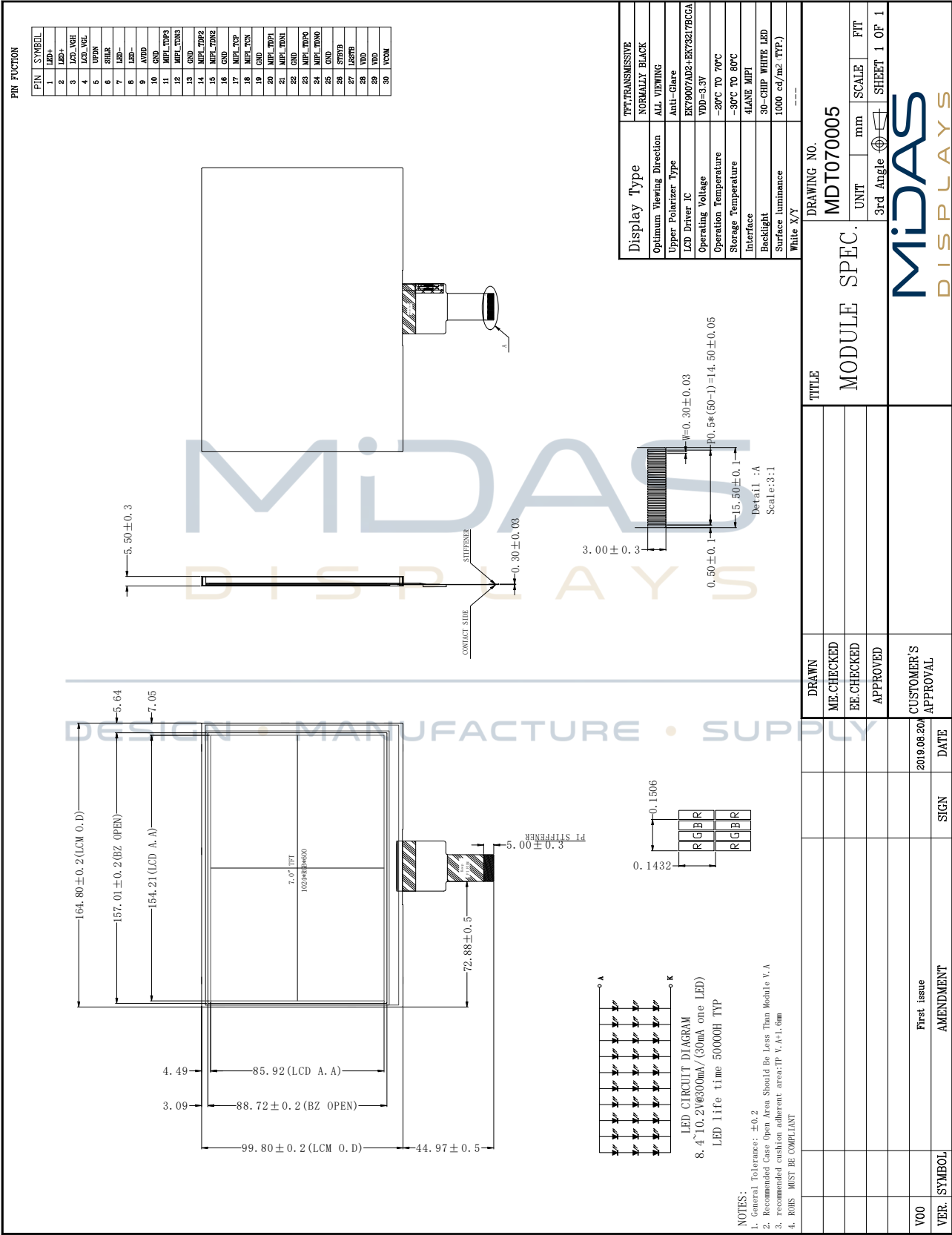
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	164.80*99.80*5.5	MM
ACTIVE SIZE (W*H)	154.21*85.92	MM
PIXEL PITCH (W*H)	0.1506*0.1432	MM
NUMBER OF DOTS	1024*600	
DIVER IC	EK79007AD2+EK73217BCGA	
INTERFACE TYPE	MIPI	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	ALL	O'CLOCK
GRAY SCALE INVERSION DIRECTION	-	O'CLOCK
BACKLIGHT TYPE	30-CHIP WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

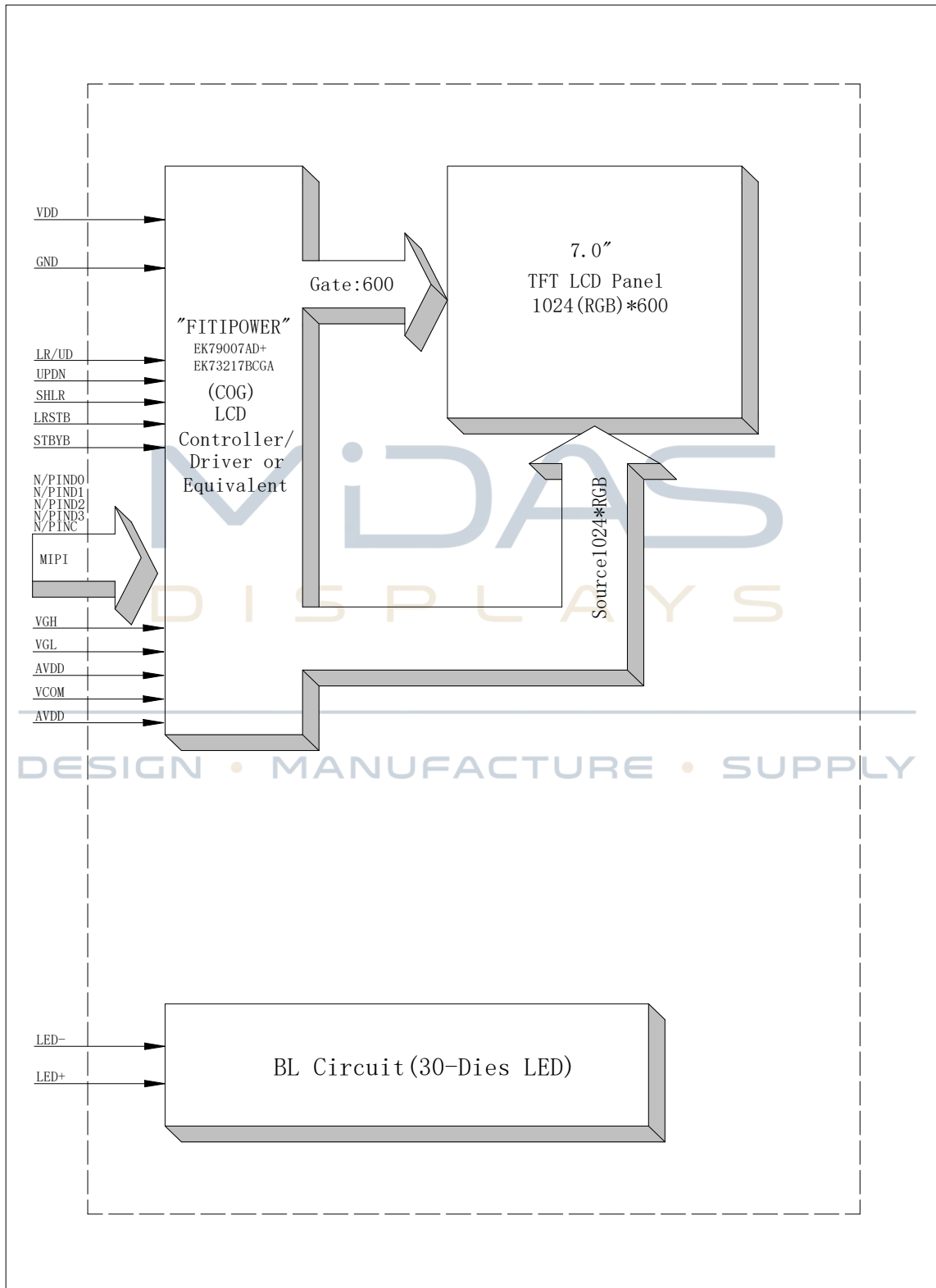
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2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	LED+	LED Anode
2	LED+	LED Anode
3	LCD_VGH	Gate ON Voltage
4	LCD_VGL	Gate OFF Voltage
5	UPDN	Vertical inversion
6	SHLR	Horizontal inversion
7	LED-	LED Cathode
8	LED-	LED Cathode
9	AVDD	Power Voltage for digital circuit
10	GND	Power ground
11	MIPI_TDP3	MIPI DATA POSITIVE SIGNAL(TDP3)
12	MIPI_TDN3	MIPI DATA NEGATIVE SIGNAL(TDN3)
13	GND	Power ground
14	MIPI_TDP2	MIPI DATA POSITIVE SIGNAL(TDP2)
15	MIPI_TDN2	MIPI DATA NEGATIVE SIGNAL(TDN2)
16	GND	Power ground
17	MIPI_TCP	MIPI CLOCK POSITIVE SIGNAL(TCP)
18	MIPI_TCN	MIPI CLOCK NEGATIVE SIGNAL(TCN)
19	GND	Power ground
20	MIPI_TDP1	MIPI DATA POSITIVE SIGNAL(TDP1)
21	MIPI_TDN1	MIPI DATA NEGATIVE SIGNAL(TDN1)
22	GND	Power ground
23	MIPI_TDP0	MIPI DATA POSITIVE SIGNAL(TDP0)
24	MIPI_TDN0	MIPI DATA NEGATIVE SIGNAL(TDN0)
25	GND	Power ground
26	STBYB	Standby mode. STBYB="H",normal operation(default) STBYB="L",timing controller,source driver will turn off,all output are GND.
27	LRSTB	Reset PIN
28	VDD	Power supply
29	VDD	Power supply
30	VCOM	Common voltage



5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	VDD	1.71	3.6	V
Supply voltage for analog	AVDD	8	13.5	V
Power supply	VGH	16	20	V
Power supply	VGL	-7	-5	V
Power supply	VCOM	3.0	4.2	V
Supply current (One LED)	I _{LED}		40	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

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6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply voltage for logic	VDD	1.71	3.3	3.6	V	
Supply voltage for analog	AVDD	8	9.0	9.1	V	
Power supply	VGH	17	18	19	V	
Power supply	VGL	-6.5	-6	-5.5	V	
Power supply	VCOM	3.0	3.15	3.3	V	
Input Voltage	V _{IL}	0	-	0.3VDD	V	
	V _{IH}	0.7 VDD	-	VDD		
Input leakage Current	I _{LKG}	-	-	-	μA	

6.2 Backlight Driving Conditions

Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	8.4	9.6	10.2	V	I _L =300mA
Current for LED Backlight	I _L		300		mA	
Power Consumption	P		2.88		W	
LED Life Time		30,000	50,000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃

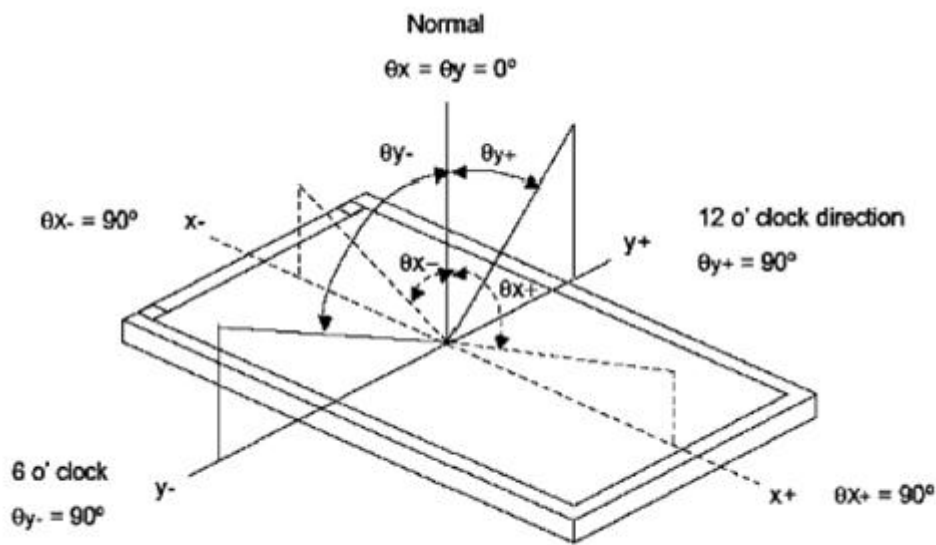


7. Optical Characteristics

ITEM		SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
				MIN	TYP.	MAX		
Luminance		L	$I_L = 300\text{mA}$	800	1000	1400	Cd/m^2	
Contrast Ratio		CR	$\theta = 0^\circ$	500	600			
Response Time		T_{ON}	25°C		25	40	ms	
		T_{OFF}						
CIE Color Coordinate	Red	X_R	Viewing normal angle					
		Y_R						
	Green	X_G						
		Y_G						
	Blue	X_B						
		Y_B						
	White	X_W						
		Y_W						
Viewing Angle	Hor.	θ_{X+}	$\text{CR} \geq 10$	80	85		Degree	
		θ_{X-}		80	85			
	Ver.	θ_{Y+}		80	85			
		θ_{Y-}		80	85			
Uniformity	Un			70	75		%	



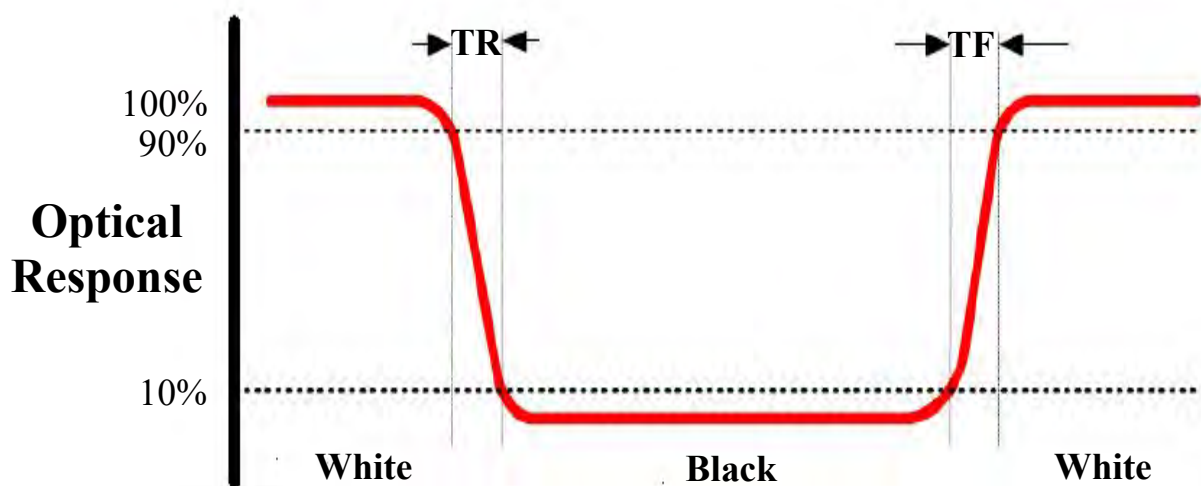
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

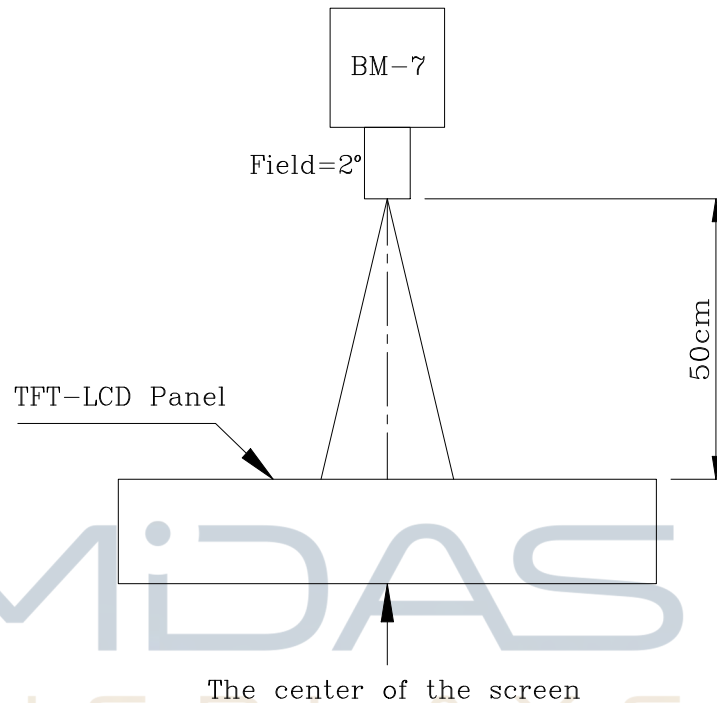
Note 3: Definition of Response Time (T_r, T_f)



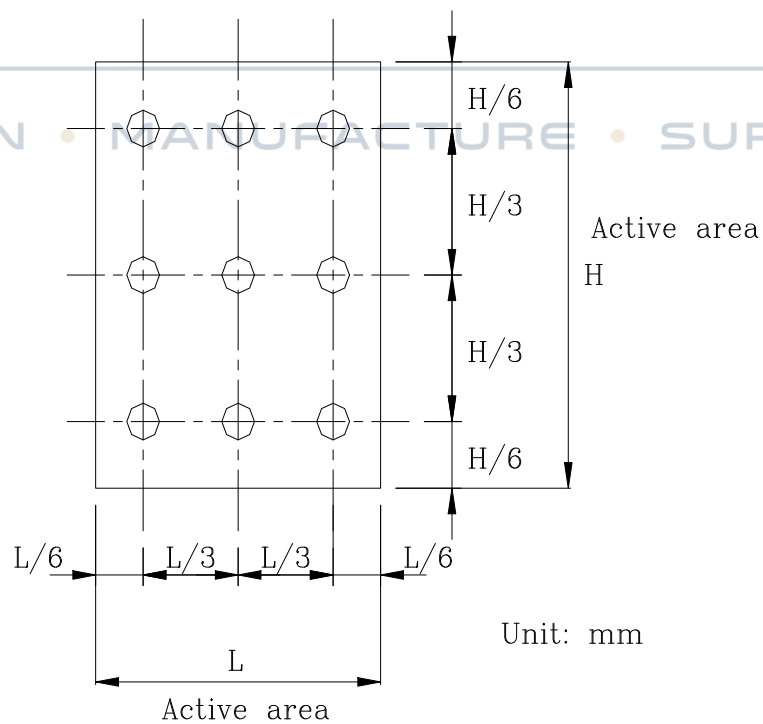
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)



②The Brightness Test Point Setup

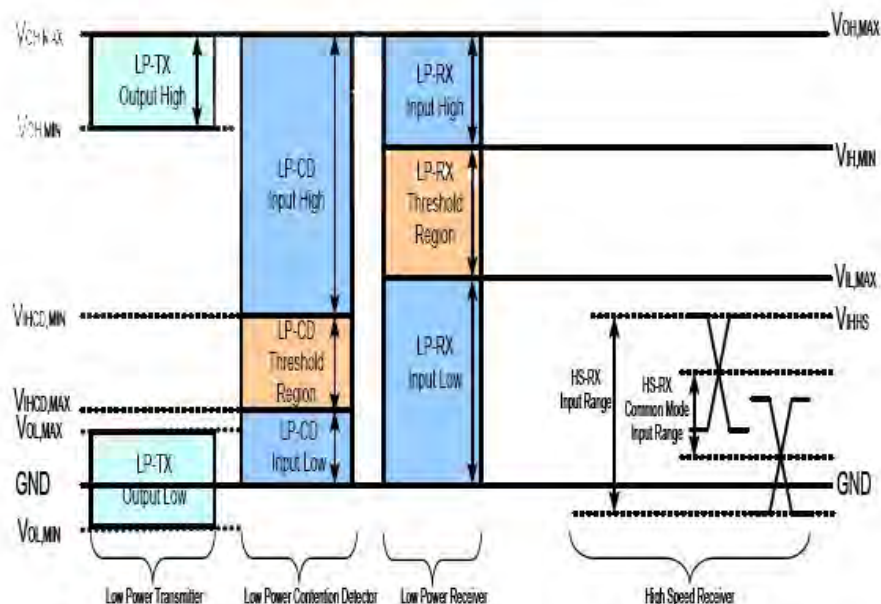


8. Timing Characteristics

8.1 MIPI Interface DC Characteristic

(VDD=VDD_IF=1.8V, AVDD=8 to 13.5V, GND=AGND=GND_IF=0V, TA=-20°C to 85°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit
MIPI Characteristics for High Speed Receiver					
Single-ended input low voltage	VILHS	-40	-	-	mV
Single-ended input high voltage	VIHHS	-	-	460	mV
Common-mode voltage	VCDRXDC	70	-	330	mV
Differential input impedance	ZID	-	100	-	ohm
HS transmit differential voltage(VOD=VDP-VDN)	VOD	140	200	250	mV
MIPI Characteristics for Low Power Mode					
Pad signal voltage range	VI	-50	-	1350	mV
Ground shift	VGNDSH	-50	-	50	mV
Logic 0 input threshold	VIL	0	-	550	mV
Logic 1 input threshold	VIH	880	-	1350	mV
Input hysteresis	VHYST	25	-	-	mV
Output low level	VOL	-50	-	50	mV
Output high level	VOH	1.1	1.2	1.3	V
Output impedance of Low Power Transmitter	ZOLP	80	100	125	ohm
Logic 0 contention threshold	VILCD,MAX	-	-	200	mV
Logic 0 contention threshold	VIHCD,MIN	450	-	-	mV

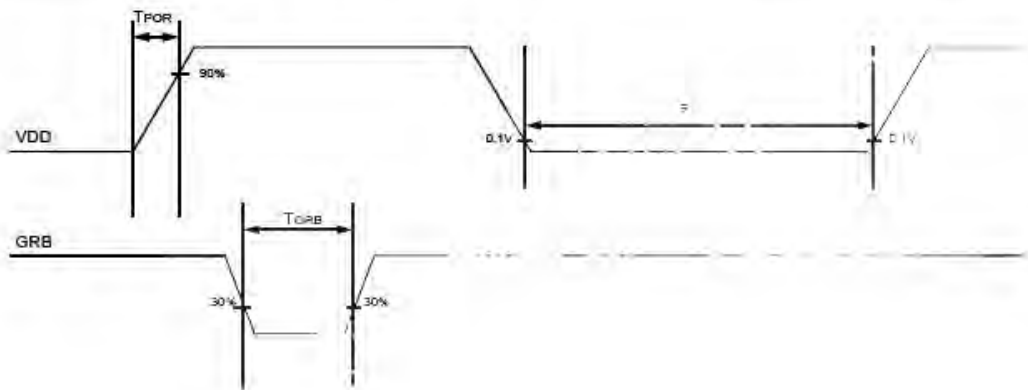


8.2 Basic DC Characteristic

(VDD=VDD_IF=1.8V, AVDD=8 to 13.5V, GND=AGND=GND_IF=0V, TA=-20 to +85°C)

VDD/GRB AC characteristic

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
VDD power slew rate	T _{POR}	-	-	20	ms	From 0 to 90% VDD
GRB active pulse width	T _{GRB}	1	-	-	ms	VDD=VDD_IF=1.8V
VDD resettle time	T _{RES}	1	-	-	s	



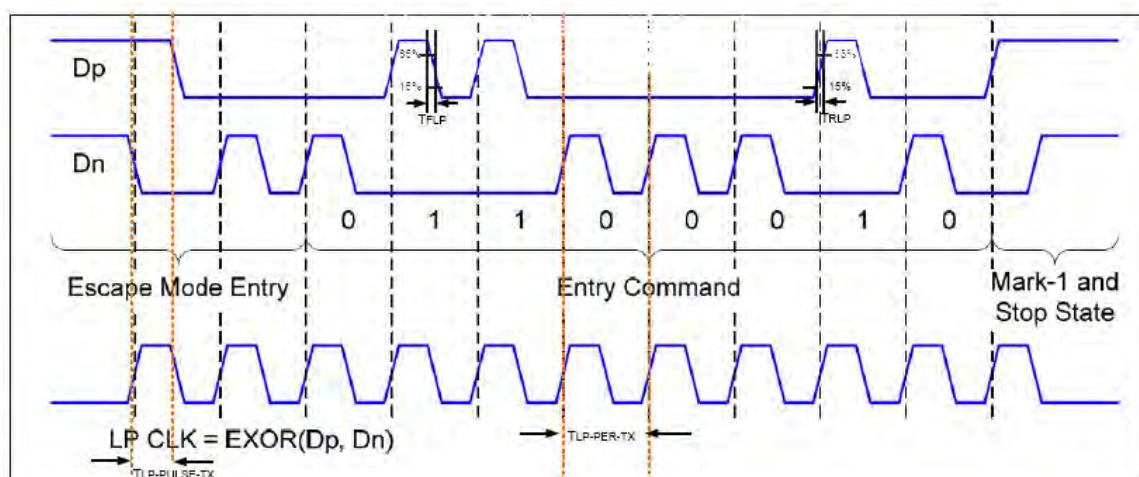
DISPLAYS

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8.3 MIPI AC Characteristic

8.3.1 LP Transmitter AC Specification

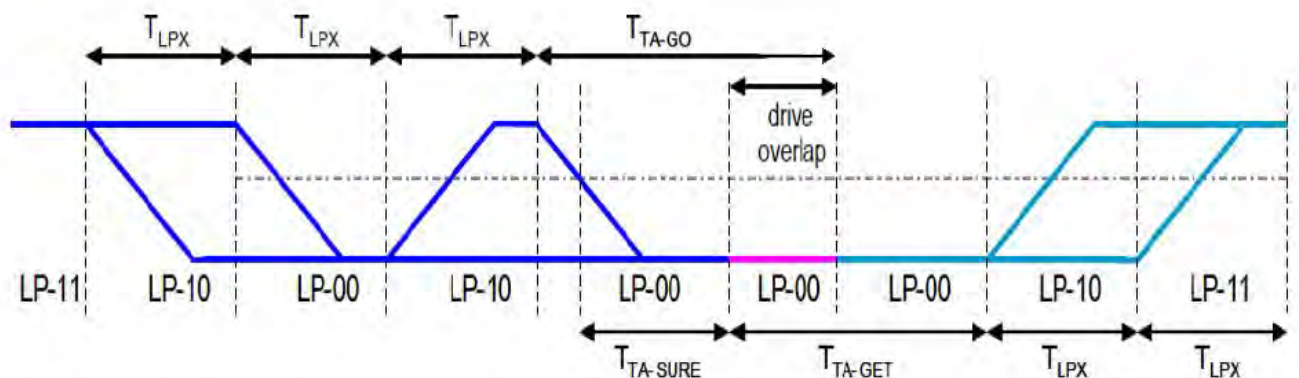
Parameter		Symbol	Min	Typ	Max	Units	Notes
15%~85% rising time and falling time		T _{RLP} /T _{FLP}	-	-	25	ns	-
30%~85% rising time and falling time		T _{REOT}	-	-	35	ns	-
Pulse width of LP exclusive-OR clock	First LP EXOR clock pulse after STOP state or Last pulse before stop state	T _{LP-PULSE-TX}	40	-	-	ns	-
	All other pulses		20	-	-	ns	-
Period of the LP EXOR clock		T _{LP-PER-TX}	90	-	-	mV/ns	-
Slew Rate @CLOAD =0pF		δ V/δ t _{SR}	30	-	500	mV/ns	-
Slew Rate @CLOAD =5pF			30	-	200	mV/ns	-
Slew Rate @CLOAD =20pF			30	-	150	mV/ns	-
Slew Rate @CLOAD =70pF			30	-	100	mV/ns	-
Load Capacitance		T _{RLP}	-	-	70	pF	-



8.3.2 Turnaround Procedure

Turnaround Procedure Operation Timing Parameters

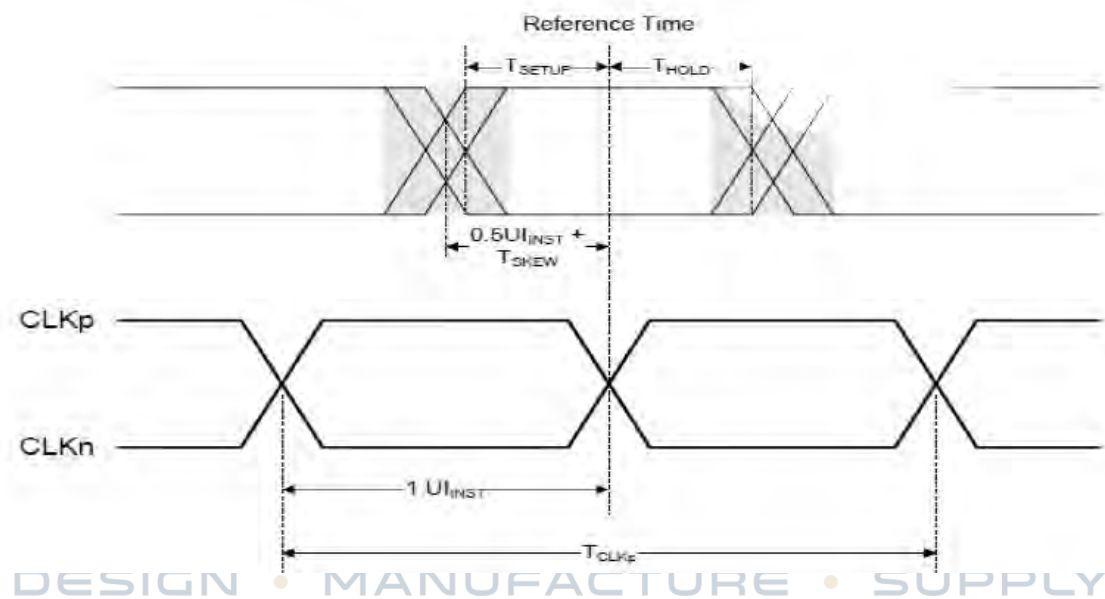
Parameter	Symbol	Min	Typ	Max	Units
Length of any Low-Power state period: Master side	T_{LPX}	50	-	75	ns
Length of any Low-Power state period: Slave side	T_{LPX}	50	55.56	58.34	ns
Ratio of $T_{LPX}(\text{Master}) / T_{LPX}(\text{Slave})$ between Master and Slave side	Ratio T_{LPX}	2/3	-	3/2	
Time-out before new TX side start driving	$T_{TA-Sure}$	T_{LPX}	-	$2T_{LPX}$	ns
Time to drive LP-00 by new TX	T_{TA-GET}	-	$5T_{LPX}$	-	ns
Time to drive LP-00 after Turnaround Request	T_{TA-GO}	-	$4T_{LPX}$	-	ns



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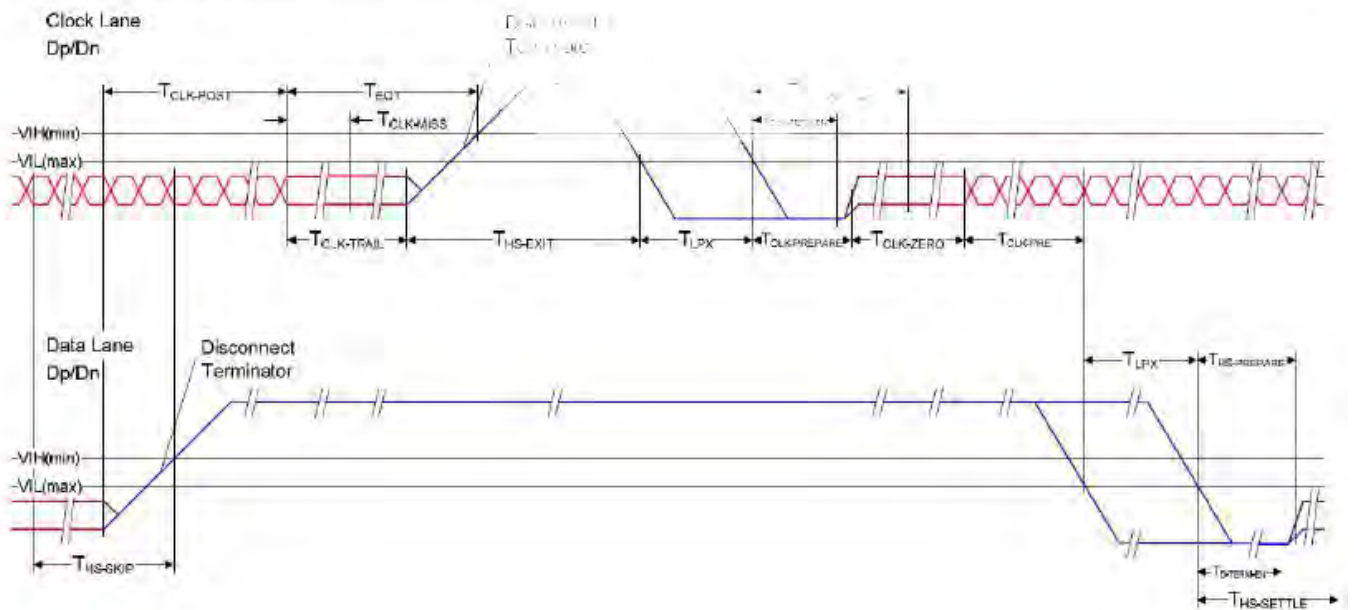
8.3.3 High Speed Transmission

Parameter	Symbol	Min	Typ	Max	Units
UI instantaneous	UI_{INST}	2	-	12.5	ns
Data to Clock Skew(measured at transmitter)	$T_{SKEW(TX)}$	-0.15	-	0.15	UI_{INST}
Data to Clock Setup time(measured at receiver)	$T_{SETUP(RX)}$	0.15	-	-	UI_{INST}
Data to Clock Hold time(measured at receiver)	$T_{HOLD(RX)}$	0.15	-	-	UI_{INST}
20%~80% rise time and fall time	T_R, T_F	150	-	-	ps
		-	-	0.2	UI_{INST}



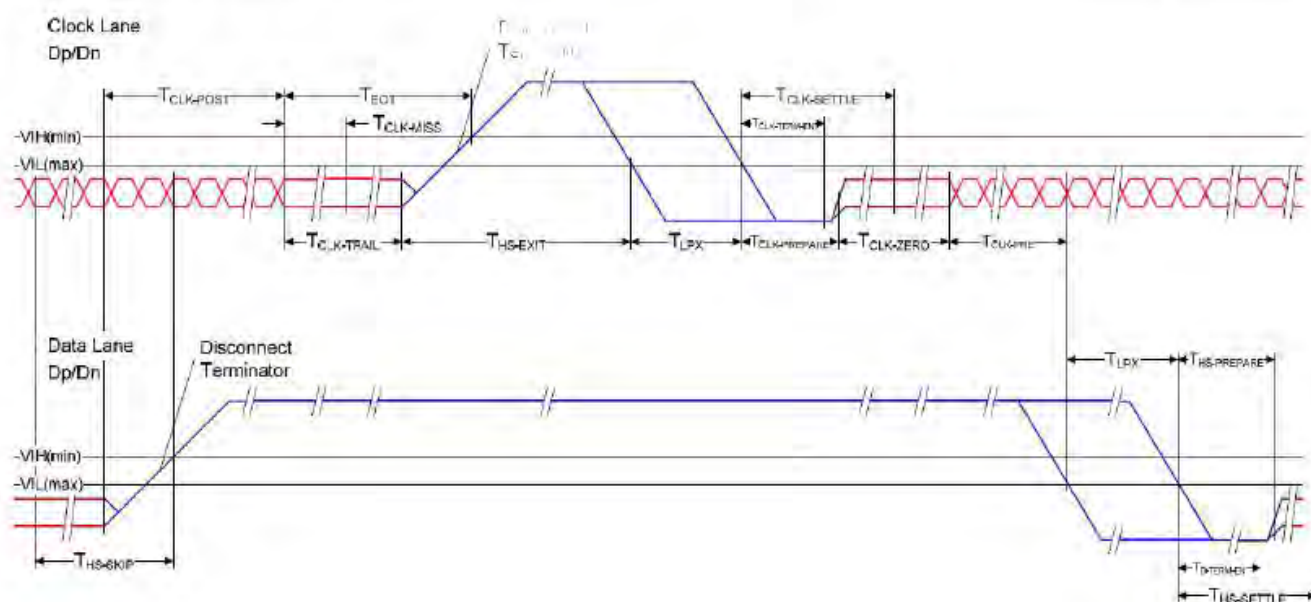
8.3.4 High Speed Transmission

Parameter	Symbol	Min	Typ	Max	Units
Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	TCLK-POST	60+52UI	-	-	ns
Detection time that the clock has stopped toggling	TCLK-MISS	-	-	60	ns
Time to drive LP-00 to prepare for HS clock transmission	TCLK-PREPARE	38	-	95	ns
Minimum lead HS-0 drive period before starting clock	TCLK-PREPARE + TCLK-ZERO	300	-	-	ns
Time to enable Clock Lane receiver line termination measured from when Dn cross V_{ILMAX}	THS-TERM-EN	-	-	38	ns
Minimum time that the HS clock must be prior to any associated data lane beginning the transmission from LP to HS mode	TCLK-PRE	8	-	-	UI
Time to drive HS differential state after last payload clock bit of a HS transmission burst	TCLK-TRAIL	60	-	-	ns

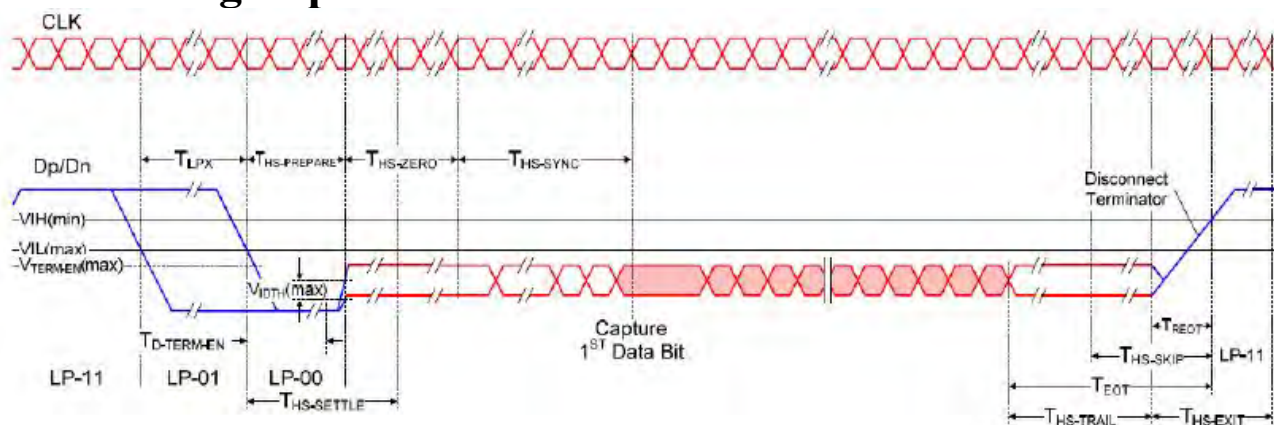


8.3.4 High Speed Clock Transmission

Parameter	Symbol	Min	Typ	Max	Units
Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	TCLK-POST	60+52UI	-	-	ns
Detection time that the clock has stopped toggling	TCLK-MISS	-	-	60	ns
Time to drive LP-00 to prepare for HS clock transmission	TCLK-PREPARE	38	-	95	ns
Minimum lead HS-0 drive period before starting clock	TCLK-PREPARE + TCLK-ZERO	300	-	-	ns
Time to enable Clock Lane receiver line termination measured from when Dn cross $V_{IL,MAX}$	THS-TERM-EN	-	-	38	ns
Minimum time that the HS clock must be prior to any associated data lane beginning the transmission from LP to HS mode	TCLK-PR	-	-	-	UI
Time to drive HS differential state after last payload clock bit of a HS transmission burst	TCLK-TRAIL	-	-	-	ns



8.3.5 High Speed Data Transmission in Bursts



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts = +70℃, 240 hours	IEC60068-21:2007 GB2423.2-2008
2	Low Temperature Operation	Ta = -20℃, 240 hours	IEC60068-2-1:2007 GB/2423.1-2008
3	High Temperature Storage	Ta = +80℃, 240 hours	IEC60068-21:2007 GB/2423.2-2008
4	Low Temperature Storage	Ta = -30℃, 240 hours	IEC60068-21:2007 GB/2423.1-2008
5	Storage at High Temperature and Humidity	Ta = +60℃, 90% RH max, 240 hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non-operation)	-30℃ 30 min~+80℃ 30 min, Change time: 5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002
7	ESD	C=150pF, R=330Ω, 5 point/panel Air: ±8Kv, 5 times; Contact: ±4Kv, 5 times (Environment: 15℃~35℃, 30%~60% RH, 86Kpa~106Kpa)	IEC61000-42:2001 GB/T17626.2-2006
8	Package Drop Test	Height: 80cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32:1990 GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm 5^{\circ}\text{C}$), normal humidity ($50\pm 10\%$ RH), and in area not exposed to direct sun light.
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10. General Precautions

10.1. Safety

- Liquid crystal is poisonous. Do not put it in your mouth. If liquid crystal touches your skin or clothes, wash it off immediately by using soap and water.

10.2. Handling

- The LCD panel is plate glass. Do not subject the panel to mechanical shock or to excessive force on its surface.
- The polarizer attached to the display is easily damaged. Please handle it carefully to avoid scratch or other damages.
- To avoid contamination on the display surface, do not touch the module surface with bare hands.
- Keep a space so that the LCD panels do not touch other components.
- Put cover board such as acrylic board on the surface of LCD panel to protect panel from damages.
- Transparent electrodes may be disconnected if you use the LCD panel under environmental conditions where the condensation of dew occurs.
- Do not leave module in direct sunlight to avoid malfunction of the ICs.

10.3. Static Electricity

- Be sure to ground module before turning on power or operating module.
- Do not apply voltage which exceeds the absolute maximum rating value.

10.4. Storage

- Store the module in a dark room where must keep at $25\pm 10^{\circ}\text{C}$ and 65%RH or less.
- Do not store the module in surroundings containing organic solvent or corrosive gas.
- Store the module in an anti-electrostatic container or bag.

10.5. Cleaning

- Do not wipe the polarizer with dry cloth. It might cause scratch.
- Only use a soft cloth with IPA to wipe the polarizer, other chemicals might permanent damage to the polarizer.



11.Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplier Midas.

11.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

11.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 1.5
Total defects: AQL = 1.5

11.3 Non-conforming Analysis & Feedback

11.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.



11.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

11.4 Agreement items

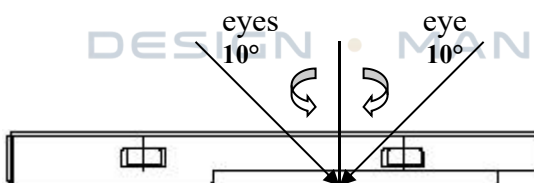
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

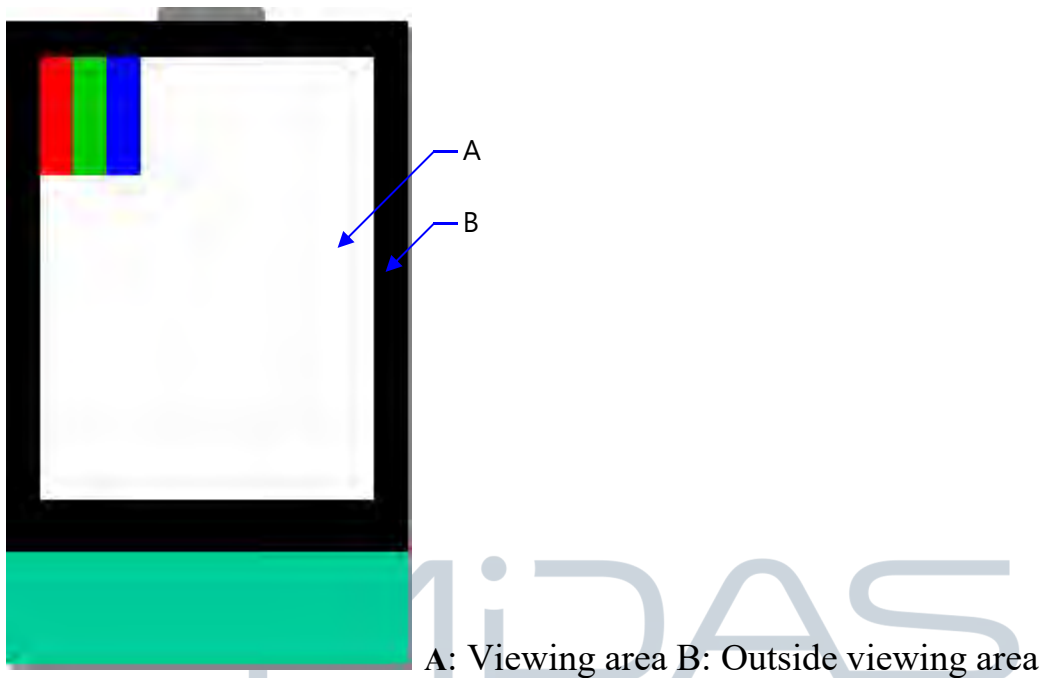
11.5 Standard of The Product Appearance Test

11.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



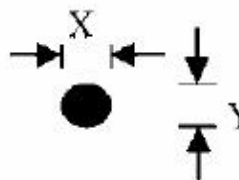
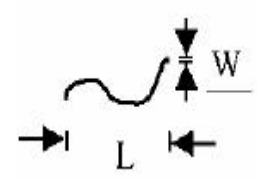
- Definition of area:

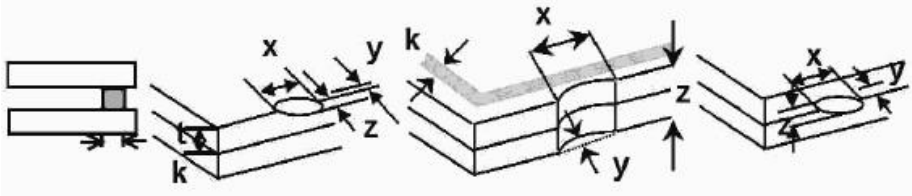
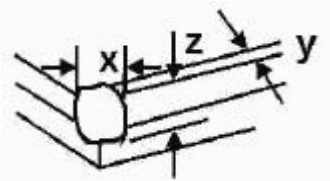


11.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

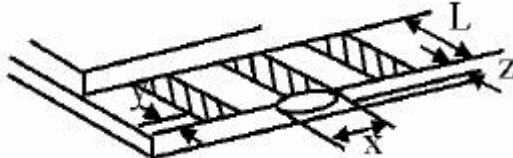
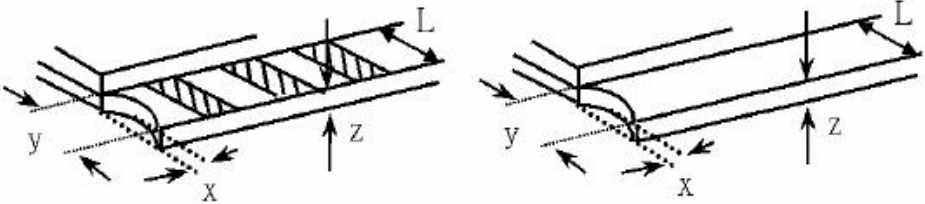
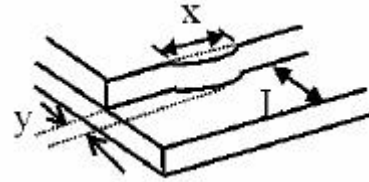
11.6 Inspection Specification

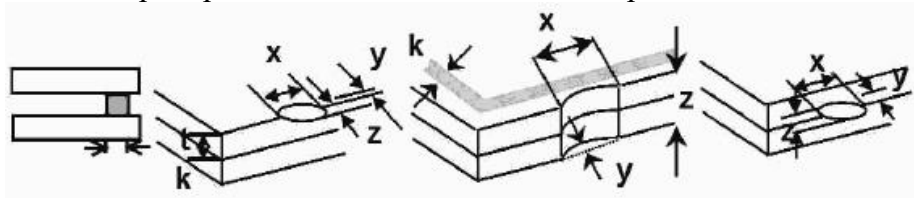
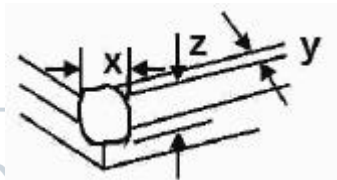
NO.	Item	Criterion	AQL														
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65														
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	1.5														
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table><tr><th>Size(mm)</th><th>Acceptable Q'ty</th></tr><tr><td>$\Phi \leq 0.10$</td><td>Accept no dense</td></tr><tr><td>$0.10 < \Phi \leq 0.20$</td><td>2</td></tr><tr><td>$0.20 < \Phi \leq 0.25$</td><td>2</td></tr><tr><td>$0.25 < \Phi \leq 0.30$</td><td>1</td></tr><tr><td>$0.30 < \Phi$</td><td>0</td></tr></table> * Densely spaced: No more than two spots within 3mm.	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	1.5		
		Size(mm)	Acceptable Q'ty														
$\Phi \leq 0.10$	Accept no dense																
$0.10 < \Phi \leq 0.20$	2																
$0.20 < \Phi \leq 0.25$	2																
$0.25 < \Phi \leq 0.30$	1																
$0.30 < \Phi$	0																
		3.2 Line type: (As following drawing)  <table><tr><th>Length(mm)</th><th>Width(mm)</th><th>Acceptable Q'ty</th></tr><tr><td>---</td><td>$W \leq 0.02$</td><td>Accept no dense</td></tr><tr><td>$L \leq 3.0$</td><td>$0.02 < W \leq 0.05$</td><td rowspan="2">2</td></tr><tr><td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.08$</td></tr><tr><td>---</td><td>$0.08 < W$</td><td>Rejection</td></tr></table> * Densely spaced: No more than two lines within 3mm.	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	1.5
Length(mm)	Width(mm)	Acceptable Q'ty															
---	$W \leq 0.02$	Accept no dense															
$L \leq 3.0$	$0.02 < W \leq 0.05$	2															
$L \leq 2.5$	$0.03 < W \leq 0.08$																
---	$0.08 < W$	Rejection															

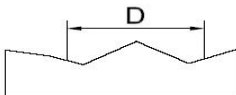
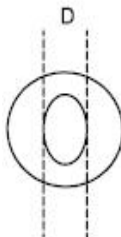
NO.	Item	Criterion			AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	1.5
			$\Phi \leq 0.20$	Accept no dense	
			$0.20 < \Phi \leq 0.50$	3	
			$0.50 < \Phi \leq 1.00$	2	
			$1.00 < \Phi$	0	
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:			1.5
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		☉ Unit: mm ☉ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack:			
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		☉ Unit: mm ☉ If there are 2 or more chips, x is the total length of each chip			

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	1.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	1.5 1.5 0.65
10	Bezel	Bezel must comply with product specifications.	1.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	1.5 1.5 1.5 1.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\leq$ 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage $\leq$ 1/2 alignment area and can not affect the function , we judge accept.	1.5 1.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	1.5 0.65



NO.	Item	Criterion	AQL																
07	Glass crack	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:  <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq 0.5\text{mm}$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> 7.2.2 Non-conductive portion:  <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq L$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged. 7.2.3 Substrate protuberance and internal crack  <table><tr><td>y: width</td><td>x: length</td></tr><tr><td>$y \leq 1/3L$</td><td>$X \leq a$</td></tr></table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	1.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:  <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$Z \leq t$</td><td>$\leq 1/2 k$ and not over viewing area</td><td>$x \leq 1/8a$</td></tr></table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack:  <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$z \leq t$</td><td>$\leq 1/2 k$ and not over viewing area</td><td>$x \leq 1/8a$</td></tr></table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	1.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	1.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	1.5										
17	Touch Panel Linearity	Less than 1.5% is acceptable.	1.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										